EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	17176	(bonding adj pad) and (semiconductor or ic or die or chip or (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 14:29
S2	980	S1 and (display)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 07:29
S3	756	S2 and (aluminum or al)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/02 07:30
S4	1	("20040166661").PN.	US-PGPUB; USPAT	OR	OFF	2005/04/02 07:30
S5	9518	(bonding adj pad) and (semiconductor or ic or die or chip or (integrated adj circuit)) and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 16:57
S6	4412	"257"/$6.ccls. and ((bonding adj pad) and (semiconductor or ic or die or chip or (integrated adj circuit)) and (al or aluminum))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 14:30
S7	2012	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 09:42
S8	1611	S7 and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 16:29

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S11	1611	S7 and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 16:29
S12	58	((bonding adj pad) WITH (protrudions or protruding)) and (semiconductor or ic or die or chip or (integrated adj circuit)) and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 16:59
S13	58	((bonding adj pad) WITH (protrutions or protruding)) and (semiconductor or ic or die or chip or (integrated adj circuit)) and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 16:59
S14	193	((bonding adj pad) WITH (protrusions or protruding)) and (semiconductor or ic or die or chip or (integrated adj circuit)) and (al or aluminum)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:26
S15	175	S14 not S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 17:00
S16	401	S7 not S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/17 17:00
S17	343	((bonding adj pad) WITH (protrusions or protruding)) and (semiconductor or ic or die or chip or (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 09:26
S18	2147	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:24

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S19	2123	S18 not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 09:44
S20	1566	257/734.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:25
S21	2146	257/784.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:25
S22	1976	257/786.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:25
S23	5101	S20 S21 S22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:25
S24	2147	257/737.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:25
S25	4663	S23 not S24	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:25
S26	343	((bonding adj pad) WITH (protrusions or protruding)) and (semiconductor or ic or die or chip or (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 11:25

EAST Search History

S27	4638	S25 not S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:26
S28	1262	S27 and ((bonding or bond) adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/14 11:26
S29	1685	S27 and ((bonding or bond) adj pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/14 11:26